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Hex Schmitt-Trigger Inverter with LSTTL Compatible Inputs

High-Performance Silicon-Gate CMOS

The MC74HCT14A may be used as a level converter for interfacing TTL or NMOS outputs to high–speed CMOS inputs.

The HCT14A is useful to "square up" slow input rise and fall times. Due to the hysteresis voltage of the Schmitt trigger, the HCT14A finds applications in noisy environments.

Features

- Output Drive Capability: 10 LSTTL Loads
- TTL/NMOS-Compatible Input Levels
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 4.5 to 5.5 V
- Low Input Current: 1.0 μA
- In Compliance With the JEDEC Standard No. 7.0 A Requirements
- Chip Complexity: 72 FETs or 18 Equivalent Gates
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant

LOGIC DIAGRAM

A1
$$\frac{1}{11}$$
 $\frac{2}{11}$ $\frac{2}{11}$ $\frac{4}{11}$ $\frac{2}{11}$ $\frac{4}{11}$ $\frac{10}{11}$ $\frac{10}{11}$ $\frac{10}{11}$ $\frac{10}{11}$ $\frac{10}{11}$ $\frac{12}{11}$ $\frac{10}{11}$ $\frac{12}{11}$ $\frac{12}{11$



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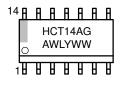


SOIC-14 NB D SUFFIX CASE 751A TSSOP-14 DT SUFFIX CASE 948G

PIN ASSIGNMENT

A1 [1●		v _{cc}
Y1 [2	13] A6
A2 [3	12] Y6
Y2 [4	11] A5
A3 [5	10] Y5
Y3 [6	9] A4
GND [7	8] Y4
			1

MARKING DIAGRAMS





SOIC-14 NB

A = Assembly Location
L, WL = Wafer Lot
Y, YY = Year
W, WW = Work Week
G or = Pb-Free Package

(Note: Microdot may be in either location)

FUNCTION TABLE

Input	Output
A	Y
L	H L

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

MAXIMUM RATINGS

Symbol	F	Parameter	Value	Unit
V _{CC}	DC Supply Voltage	(Referenced to GND)	-0.5 to +7.0	V
VI	DC Input Voltage	(Referenced to GND)	–0.5 to V _{CC} + 0.5	V
V _O	DC Output Voltage	(Referenced to GND)	-0.5 to $V_{CC} + 0.5$	V
I _{IK}	DC Input Diode Current		±20	mA
I _{OK}	DC Output Diode Current		±25	mA
Io	DC Output Sink Current		±25	mA
I _{CC}	DC Supply Current per Supply Pin		±50	mA
I _{GND}	DC Ground Current per Ground Pin		±50	mA
T _{STG}	Storage Temperature Range		-65 to +150	°C
T_L	Lead Temperature, 1 mm from Case for	or 10 Seconds	260	°C
T_J	Junction Temperature under Bias		+150	°C
θЈА	Thermal Resistance	SOIC TSSOP	125 170	°C/W
P _D	Power Dissipation in Still Air at 85°C	SOIC TSSOP	500 450	mW
MSL	Moisture Sensitivity		Level 1	
F _R	Flammability Rating	Oxygen Index: 30% – 35%	UL 94 V-0 @ 0.125 in	
V _{ESD}	ESD Withstand Voltage	Human Body Model (Note 1) Machine Model (Note 2) Charged Device Model (Note 3)	> 4000 > 300 > 1000	V
I _{Latchup}	Latchup Performance	Above V _{CC} and Below GND at 85°C (Note 4)	±300	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. Tested to EIA/JESD22-A114-A.
- 2. Tested to EIA/JESD22-A115-A.
- 3. Tested to JESD22-C101-A.
- 4. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	DC Supply Voltage (Referenced to GN	D) 4.5	5.5	V
V_I, V_O	DC Input Voltage, Output Voltage (Referenced to GN	D) 0	V _{CC}	V
T _A	Operating Temperature, All Package Types	-55	+125	°C
t _r , t _f	Input Rise and Fall Time (Figure 1)	_	(Note 5)	ns

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability. 5. No Limit when $V_I \approx 50\%~V_{CC},~I_{CC} > 1~mA$.

- 6. Unused inputs may not be left open. All inputs must be tied to a high-logic voltage level or a low-logic input voltage level.

DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

				Temperature Limit						
			V _{CC}	-55°C to 25°C ≤8		≤85°C ≤125°C		25°C	1	
Symbol	Parameter	Test Conditions	Volts	Min	Max	Min	Max	Min	Max	Unit
V _{T+} max	Maximum Positive–Going Input Threshold Voltage	$V_O = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V}$ $ I_{out} \le 20 \mu\text{A}$	4.5 5.5		1.9 2.1		1.9 2.1		1.9 2.1	٧
V_{T+} min	Minimum Positive-Going Input Threshold Voltage	$V_O = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V}$ $ I_{out} \le 20 \mu\text{A}$	4.5 5.5	1.2 1.4		1.2 1.4		1.2 1.4		٧
V_{T-} max	Maximum Negative–Going Input Threshold Voltage	$V_O = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V}$ $ I_{out} \le 20 \mu\text{A}$	4.5 5.5		1.2 1.4		1.2 1.4		1.2 1.4	
V_{T-} min	Minimum Negative-Going Input Threshold Voltage	$V_O = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V}$ $ I_{out} \le 20 \mu\text{A}$	4.5 5.5	0.5 0.6		0.5 0.6		0.5 0.6		
V _H max	Maximum Hysteresis Voltage	$V_O = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V}$ $ I_{out} \le 20 \mu\text{A}$	4.5 5.5		1.4 1.5		1.4 1.5		1.4 1.5	
V _H min	Minimum Hysteresis Voltage	$V_O = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V}$ $ I_{out} \le 20 \mu\text{A}$	4.5 5.5	0.4 0.4		0.4 0.4		0.4 0 4		
V _{OH}	Minimum High-Level Output Voltage	$V_I < V_{T-}$ min $ I_{out} \le 20 \mu A$	4.5 5.5	4.4 5.4		4.4 5.4		4.4 5.4		V
		$V_{I} < V_{T-}$ min $ I_{out} \le 4.0$ mA	4.5	3.98		3.84		3.7		-
V _{OL}	Maximum Low–Level Output Voltage	$V_1 \ge V_{T+} max$ $ I_{out} \le 20 \mu A$	4.5 5.5		0.1 0.1		0.1 0.1		0.1 0.1	V
		$V_l \ge V_{T+} max$ $ I_{out} \le 4.0 mA$	4.5		0.26		0.33		0.4	-
I _{IK}	Maximum Input Leakage Current	V _I = V _{CC} or GND	5.5		±0.1		±1.0		±1.0	μΑ
I _{CC}	Maximum Quiescent Supply Current (per package)	$V_I = V_{CC}$ or GND $I_{out} = 0 \mu A$	5.5		1.0		10		40	μΑ
				ì	≥ -55°C	•	25°	C to 12	5°C	
ΔI_{CC}	Additional Quiescent Supply Current	V_{I} = 2.4 V, Any One Input V_{I} = V_{CC} or GND, Other Inputs I_{out} = 0 μA	5.5	2.9 2.4			mA			

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

AC CHARACTERISTICS ($C_L = 50 \text{ pF}$; Input $t_r = t_f = 6.0 \text{ ns}$)

				Guaranteed Limit						
				−55°C	to 25°C	≤8	5°C	≤12	25°C	
Symbol	Parameter	Test Conditions	Figures	Min	Max	Min	Max	Min	Max	Unit
t _{PLH} , t _{PHL}	Maximum Propagation Delay, Input A to Output Y (L to H)	$V_{CC} = 5.0 \text{ V} \pm 10\%$ $C_L = 50 \text{ pF}, \text{ Input } t_r = t_f = 6.0 \text{ ns}$	1 & 2		32		40		48	ns
t _{TLH} , t _{THL}	Maximum Output Transition Time, Any Output	$V_{CC} = 5.0 \text{ V} \pm 10\%$ $C_L = 50 \text{ pF}, \text{ Input } t_r = t_f = 6.0 \text{ ns}$	1 & 2		15		19		22	ns

		Typical @ 25°C, V _{CC} = 5.0 V	
C_{PD}	Power Dissipation Capacitance, per Inverter (Note 7)	32	pF

^{7.} Used to determine the no–load dynamic power consumption: $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$.

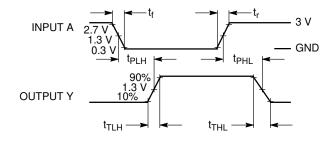
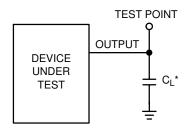


Figure 1. Switching Waveforms



*Includes all probe and jig capacitance.

Figure 2. Test Circuit

ORDERING INFORMATION

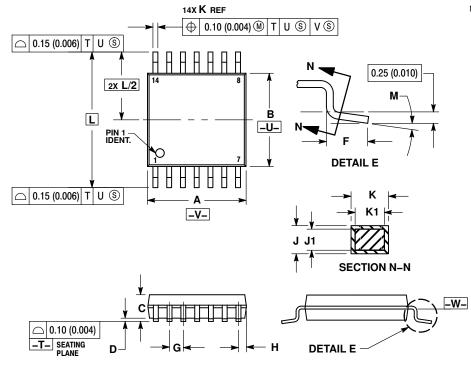
Device	Package	Shipping [†]
MC74HCT14ADG	SOIC-14 NB	55 Units / Rail
NLV74HCT14ADG*	(Pb-Free)	55 Utilis / Hall
MC74HCT14ADR2G	SOIC-14 NB	2500 / Tana & Daal
NLV74HCT14ADR2G*	(Pb-Free)	2500 / Tape & Reel
MC74HCT14ADTR2G	TSSOP-14	2500 / Tape & Reel
NLV74HCT14ADTR2G*	(Pb-Free)	2500 / Tape & neet

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

PACKAGE DIMENSIONS

TSSOP-14 CASE 948G **ISSUE B**



NOTES:

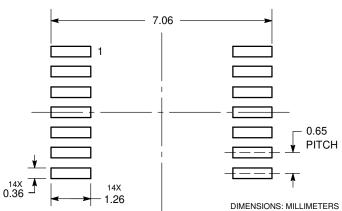
- DTES:
 1. DIMENSIONING AND TOLERANCING PER
 ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD
 FLASH, PROTRUSIONS OR GATE BURRS.
 MOLD FLASH OR GATE BURRS SHALL NOT
 EXCEED 0.15 (0.006) PER SIDE.
 4. DIMENSION B DOES NOT INCLUDE
- 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.

 6. TERMINAL INLIMBERS ARE SHOWN FOR
- 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY. 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W–.

	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	4.90	5.10	0.193	0.200	
В	4.30	4.50	0.169	0.177	
С		1.20		0.047	
D	0.05	0.15	0.002	0.006	
F	0.50	0.75	0.020	0.030	
G	0.65	65 BSC 0.026 B		BSC	
Н	0.50	0.60	0.020	0.024	
J	0.09	0.20	0.004	0.008	
J1	0.09	0.16	0.004	0.006	
K	0.19	0.30	0.007	0.012	
K1	0.19	0.25	0.007	0.010	
L	6.40	BSC	0.252 BSC		
М	0°	8 °	0°	8 °	

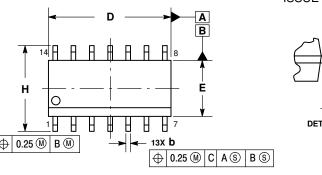
SOLDERING FOOTPRINT*

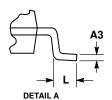


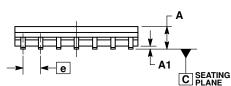
*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

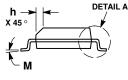
PACKAGE DIMENSIONS

SOIC-14 NB CASE 751A-03 ISSUE K







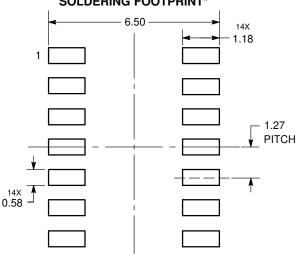


NOTES:

- 1. DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS.
- 2. DIMENSION & DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
- 5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	1.35	1.75	0.054	0.068	
A1	0.10	0.25	0.004	0.010	
A3	0.19	0.25	0.008	0.010	
b	0.35	0.49	0.014	0.019	
D	8.55	8.75	0.337	0.344	
Е	3.80	4.00	0.150	0.157	
е	1.27	BSC	0.050	BSC	
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.019	
L	0.40	1.25	0.016	0.049	
М	0 °	7°	0 °	7°	

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

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^{*}For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.